CMKD3003DO

SURFACE MOUNT
DUAL, ISOLATED, OPPOSING
LOW LEAKAGE SILICON
SWITCHING DIODES





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMKD3003DO contains two (2) Isolated Opposing Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in a ULTRAmini™ surface mount package. These devices are designed for switching applications requiring extremely low leakage.

MARKING CODE: C303

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	V_{R}	180	V
Average Rectified Current	IO	200	mA
Continuous Forward Current	I _F	600	mA
Peak Repetitive Forward Current	I _{FRM}	700	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	2.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

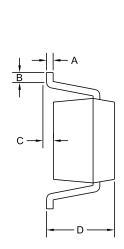
ELECTRICAL	CHARACTERISTICS PER DIOD	E: (T _A =25°C unless	otherwise noted)	
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{R}	V _R =125V		1.0	nA
I_{R}	V _R =125V, T _A =150°C		3.0	μΑ
I_{R}	V _R =180V		10	nA
I_{R}	V _R =180V, T _A =150°C		5.0	μΑ
BV_R	I _R =5.0μA	200		V
V_{F}	I _F =1.0mA	0.62	0.72	V
VF	I _F =10mA	0.72	0.83	V
V_{F}	I _F =50mA	0.80	0.89	V
V_{F}	I _F =100mA	0.83	0.93	V
V_{F}	I _F =200mA	0.87	1.10	V
V_{F}	I _F =300mA	0.90	1.15	V
Ст	$V_{R}=0$, f=1.0MHz		4.0	pF

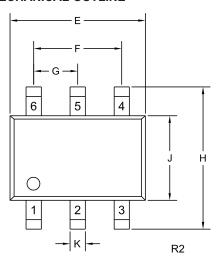
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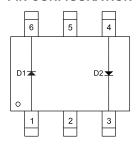


SOT-363 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.004	0.010	0.10	0.25			
В	0.005	-	0.12	-			
С	0.000	0.004	0.00	0.10			
D	0.031	0.043	0.80	1.10			
E	0.071	0.087	1.80	2.20			
F	0.051		1.30				
G	0.026		0.65				
Н	0.075	0.091	1.90	2.30			
J	0.043	0.055	1.10	1.40			
K	0.006	0.012	0.15	0.30			

SOT-363 (REV: R2)

LEAD CODE:

- 1) Anode D1
- 2) NC
- 3) Cathode D2
- 4) Anode D2
- 5) NC
- 6) Cathode D1

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R0 (19-September 2011)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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